

## IN THE SPECIFICATION

Please Amend the first paragraph of the specification beginning on Page 1, line 9 and entitled "**CROSS-REFERENCE TO RELATED APPLICATIONS**" in accordance with the following mark-up copy:

The present application is a continuation-in-part of the following co-pending U.S. Patent applications: "IMPRINTED INTEGRATED CIRCUIT SUBSTRATE AND METHOD FOR IMPRINTING AN INTEGRATED CIRCUIT SUBSTRATE" Serial number 09/884,193 ~~09/931,144~~ filed June 19<sup>th</sup>, 2001 ~~August 16<sup>th</sup>, 2001~~; "INTEGRATED CIRCUIT SUBSTRATE HAVING LASER-EMBEDDED CONDUCTIVE PATTERNS AND METHOD THEREFOR", serial number 10/138,225 filed May 1, 2002; "SOLDERABLE INJECTION-MOLDED INTEGRATED CIRCUIT SUBSTRATE AND METHOD THEREFOR" serial number 09/931,144, filed August 16, 2001; and "INTEGRATED CIRCUIT FILM SUBSTRATE HAVING EMBEDDED CONDUCTIVE PATTERNS AND VIAS", serial number 10/261,868 filed October 1, 2002. Each of the above-listed parent applications has at least one common inventor and is assigned to the same assignee. The specifications of all of the above-listed parent applications are incorporated herein by reference.

It is not believed that this Amendment letter requires any fee,  
but if there are any fees incurred by this Amendment Letter, please  
deduct them from our Deposit Account NO. 23-0830.

Respectfully submitted,



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